



## Final Product Change Notification

201801009F01

**Issue Date:** 17-Mar-2018  
**Effective Date:** 25-Jun-2018

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# QUALITY

### Management Summary

Cu Wire is being added as a wirebond material option for LPC18xx, LPC18x0, LPC43xx and LPC43x0 in BGA packages at assembly site NXP-ATKH.

### Change Category

- |  |  |  |   |   |
|--|--|--|---|---|
| <input type="checkbox"/> Wafer Fab Process   | <input type="checkbox"/> Assembly Process              | <input type="checkbox"/> Product Marking           | <input type="checkbox"/> Test Location  | <input type="checkbox"/> Design                         |
| <input type="checkbox"/> Wafer Fab Materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Mechanical Specification  | <input type="checkbox"/> Test Process   | <input type="checkbox"/> Errata                         |
| <input type="checkbox"/> Wafer Fab Location  | <input type="checkbox"/> Assembly Location             | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test Equipment | <input type="checkbox"/> Electrical spec./Test coverage |

LPC18xx, LPC43xx BGA  
Package Cu Wire  
Qualification for NXP-  
ATKH

### Details of this Change

Copper wire has been qualified and will be added as a wirebond material. To support a robust wirebond process the mold compound has also changed. Upon effective date, NXP will begin shipping product with copper wire.

See attached Self Qualification Reports (SQR) for details of the affected part numbers, material changes and qualification test results.

Samples of the following superset part numbers will be available.

LPC1830FET100, LPC1850FET180, LPC1850FET256,  
LPC4350FET180, LPC4350FET256, LPC4370FET100,  
LPC1857FET256, LPC1857JBD208, LPC1857JET256  
LPC4367JBD208, LPC4367JET100, LPC4367JET256

### Why do we Implement this Change

Adding Copper wire is required to mitigate against raw material cost increases and for supply assurance. The die attach material, and mold compound change enable a robust Cu wirebond process.

### Identification of Affected Products

Top side marking

Product version is incremented. See marking details in attached Self Qualification Report (SQR) document.

### Product Availability

#### Sample Information

Samples are available from 30-Mar-2018

Sample requests can be sent to the email address below in Contact and Support.

#### Production

Planned first shipment 25-Jun-2018

### Impact

Wire composition and mold compound are the only changes. No Impact to form, fit or function. Reliability is equivalent or improved.

#### Data Sheet Revision

No impact to existing datasheet

#### Disposition of Old Products

Existing inventory will be shipped until depleted

### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 16-Apr-2018.

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Tim Camenzind  
**Position** Senior Quality Engineer  
**e-mail address** tim.camenzind@nxp.com

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NXP Quality Management Team.

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**Affected Part Numbers**

LPC1850FET256,551  
LPC18S37JET100E  
LPC1833FET256,551  
LPC1837FET256,551  
LPC1857FET256,551  
LPC4330FET256,551  
LPC4350FET256,551  
LPC4330FET180,551  
LPC4357FET256,551  
LPC4337FET256,551  
LPC4333FET256,551  
LPC4357JET256,551  
LPC4337JET256,551  
LPC4333JET256,551  
LPC4370FET256E  
LPC4370FET100E  
LPC4333JET100E  
LPC4337JET100E  
LPC1812JET100E  
LPC1833JET100E  
LPC1837JET100E  
LPC4367JET256E  
LPC18S30FET256E  
LPC43S37JET100E  
LPC43S57JET256E